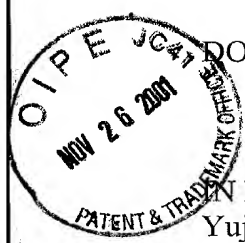


#4 Receipt



DOCKET NUMBER: 214306US2RD/pmh

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:  
Yuji ISEKI, et al.

: GROUP: 2811

SERIAL NUMBER: 09/960,338

: ATTENTION:  
Application Division  
Customer Corrections

FILED: SEPTEMBER 24, 2001

FOR: HIGH FREQUENCY FLIP CHIP MODULE AND ASSEMBLING METHOD  
THEREOF

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents  
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Sir:

The Patent Office is requested to provide a corrected Official Filing Receipt for the attached. If you have any questions, please do not hesitate to contact us.

No fees are required. However, in the event that a fee is required, please charge the appropriate amount to our Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

Marvin J. Spivak  
Attorney of Record  
Registration Number 24,913

Surinder Sachar  
Registration No. 34,423



**22850**

Tel. (703) 413-3000  
Fax. (703) 413-2220  
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/960,338	09/24/2001	2811	710	214306US2RD	21	20	2

CONFIRMATION NO. 4632

22850  
OBLON SPIVAK MCCLELLAND MAIER & NEUSTADT PC  
FOURTH FLOOR  
1755 JEFFERSON DAVIS HIGHWAY  
ARLINGTON, VA 22202

FILING RECEIPT



\*OC000000006954118\*



Date Mailed: 10/23/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Juji Iseki, Kanagawa, JAPAN;  
Naoko Ono, Tokyo, JAPAN;  
Keiichi Yamaguchi, Kanagawa, JAPAN;

Assignment For Published Patent Application

KABUSHIKI KAISHA TOSHIBA, Tokyo, JAPAN;

Domestic Priority data as claimed by applicant

Foreign Applications

JAPAN P2000-294053 09/27/2000

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Projected Publication Date: 03/28/2002

Non-Publication Request: No

Early Publication Request: No

Title

High frequency flip chip module and assembling method thereof

Preliminary Class

257

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OCT 25 2001  
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PLEASE NOTE THAT THE APPLICANT'S NAME IS INCORRECT. IT SHOULD READ AS FOLLOWS:

YUJI ISEKI, KANAGAWA, JAPAN